

IN THE CLAIMS:

All of the claims that remain pending and under consideration in the above-referenced application are reproduced below, in clean form, for the sake of clarity. Also, a marked-up version of each amended claim is enclosed herewith to clearly show each change that has been made thereto.

Please enter the claims as follows:

B 1. (Amended) In a method of producing semiconductor chips wherein the chips are at least fabricated and characterized, the improvement comprising:
marking with identifying indicia only those chips which are characterized for use by exposing selected locations of at least one of a surface of at least one semiconductor chip and an energy-reactive marking material to energy to cause said energy-reactive marking material to adhere to said surface.

2. The method of claim 1, wherein said marking is effected following packaging of the chips.

3. The method of claim 1, wherein said marking is effected as the last step in the production process.

4. The method of claim 1, wherein said marking comprises laser marking.

B TP4 5. (Twice amended) The method of claim 1, wherein said marking comprises:
providing said energy-reactive marking material over said surface of said at least one semiconductor chip.

6. The method of claim 5, wherein said exposing is effected without substantially creating an imprint in said surface.

B3

7. (Amended) A method for producing semiconductor chips, comprising:
fabricating at least one semiconductor chip;
determining whether said at least one semiconductor chip is suitable for use; and
marking said at least one semiconductor chip only if said at least one semiconductor chip is
determined to be suitable for use by exposing selected locations of at least one of a
surface of said at least one semiconductor chip and an energy-reactive marking material
to energy to cause said energy-reactive marking material to adhere to said surface.

8. The method of claim 7, further comprising packaging said at least one semiconductor
chip.

9. The method of claim 7, wherein said marking is effected as the last step in the
production process.

10. The method of claim 7, wherein said marking comprises laser marking.

B4 174

11. (Amended) The method of claim 7, wherein said marking comprises:
providing said energy-reactive marking material over at least a portion of said surface of said at
least one semiconductor chip.

12. The method of claim 11, wherein said exposing is effected without creating an
imprint in said surface.

B5
13. (Twice amended) A method for producing semiconductor chips, comprising:
providing at least one semiconductor chip which has been characterized as suitable for use and at
least one semiconductor chip which has been characterized as unsuitable for use; and
marking with identifying indicia only said at least one semiconductor chip which has been
characterized as suitable for use by exposing selected locations of at least one of a surface
of said at least one semiconductor chip and an energy-reactive marking material to energy
to cause said energy-reactive marking material to adhere to said surface.

14. The method of claim 13, wherein said providing comprises providing at least one
packaged semiconductor chip which has been characterized as suitable for use and at least one
packaged semiconductor chip which has been characterized as unsuitable for use.

15. The method of claim 13, wherein said marking is effected as the last step in the
production process.

16. The method of claim 13, wherein said marking comprises laser marking.

B6
17. (Amended) The method of claim 13, wherein said marking comprises:
providing said energy-reactive marking material over at least a portion of said surface of said at
least one semiconductor chip which has been characterized as suitable for use.

18. The method of claim 17, wherein said exposing is effected without forming an
imprint in said surface.

B7
19. (Amended) The method of claim 13, further comprising comparing said identifying
indicia to an identifying indicia model.

20. (Amended) The method of claim 19, further comprising determining whether said
identifying indicia substantially matches said identifying indicia model.

CMX
B

21. (Amended) The method of claim 20, further comprising rejecting said at least one semiconductor chip which has been characterized as suitable for use if its respective identifying indicia does not substantially match said identifying indicia model.

B8

22. (Twice amended) The method of claim 21, further comprising removing said identifying indicia which does not substantially match said identifying indicia model from said at least one rejected semiconductor chip which has been characterized as suitable for use.

23. (Twice amended) The method of claim 22, further comprising remarking said at least one rejected semiconductor chip which has been characterized as suitable for use.
